

# HFS29

# IGBT MODULE



File No.: E314528



### Typical Applications

Welding machine, Invertor, UPS, etc

### Features

- Half-bridge
- 1200V SPT<sup>+</sup> IGBT
- Built-in Fast free-wheeling diodes
- DCB base plate
- Environmental friendly product (RoHS compliant)

## DESCRIPTION

With output rated current at 150A, 200A, 300A, HFS29 is a high integrated, small package and user friendly IGBT module, which is ideal for the applications such as the welding machine, invertor, UPS, etc. Each module consists of two IGBTs in a half bridge configuration. All components and inner connectors are isolated from the baseplate.

## PRECAUTIONS

1. In order to get effective heat dissipation, heat sink flatness should be between -50µm and 100µm. It is important to apply thermally conductive grease with 100 to 200µm on the contact surface, where attached to the heat sink.
2. Keep the module from being damaged by the static electricity.

## ORDERING INFORMATION

Type	HFS29 /	PM	150	D	120	(SA)
Module	PM: IGBT module					
Output rating current	150: 150A    200: 200A    300: 300A					
Unit numbers	D: Dual(half bridge)					
IGBT Vces voltage	120: 1200V					
IGBT type	(SA): SPT <sup>+</sup>					

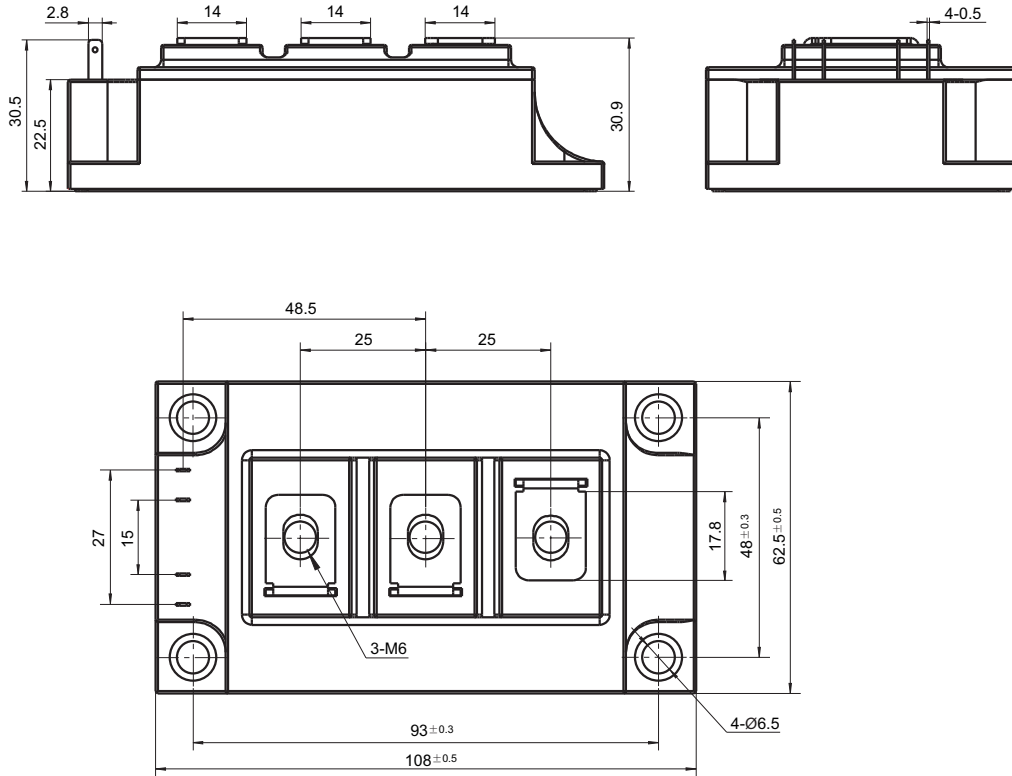


HONAF A RELAY

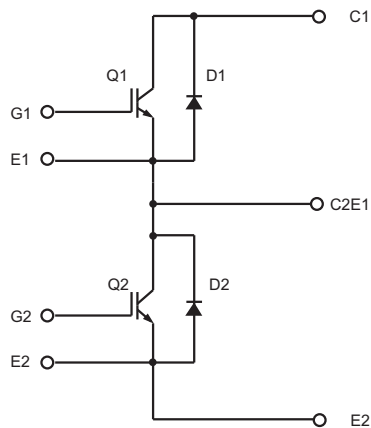
ISO9001, ISO/TS16949, ISO14001, OHSAS18001, IECQ QC 080000 CERTIFIED

2009 Rev. 1.00

Outline Dimensions



Circuit Diagram



# HFS29/PM150D120(SA)

## MAXIMUM RATINGS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Rating	Unit
V <sub>CES</sub>	Collector-emitter voltage	G, E short	1200	V
V <sub>GES</sub>	Gate-emitter voltage	C, E short	±20	V
I <sub>c</sub>	Collector current	T <sub>c</sub> =80°C	165	A
I <sub>CP</sub>	Peak collector current		300	A
T <sub>PSC</sub>	Short circuit protection time	V <sub>CC</sub> =900V; V <sub>CEM</sub> <1200V V <sub>GE</sub> ≤15V; T <sub>j</sub> ≤125°C	10	s
V <sub>iso</sub>	Isolation voltage		2500	VAC
T <sub>j</sub>	Junction temperature		-40 ~ 150	°C
T <sub>stg</sub>	Storage temperature		-40 ~ 125	°C
I <sub>F</sub>	Diode forward current	T <sub>c</sub> =25°C(80°C)	150(105)	A
I <sub>FM</sub>	Diode peak forward current	T <sub>j</sub> ≤150°C	300	A

## ELECTRICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Min.	Typ.	Max.	Units
I <sub>CES</sub>	Collector-emitter voltage	V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V		0.1	1.0	mA
I <sub>GES</sub>	Gate-emitter leakage current	V <sub>GE</sub> =±20V, V <sub>CE</sub> =0V, T <sub>j</sub> =125°C	-200		200	μA
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	I <sub>c</sub> =3mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>j</sub> =25°C	5	6.2	7	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>c</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =25°C		1.8		V
		I <sub>c</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =125°C		2.0		V
C <sub>ies</sub>	Input capacitance	V <sub>GE</sub> =0V, V <sub>CE</sub> =25V, f=1MHz		16		nF
C <sub>oes</sub>				1.2		
C <sub>res</sub>				0.6		
Q <sub>G</sub>	Total gate charge			1560		nC
R <sub>Gint</sub>	Resistance			4		Ω
E <sub>on</sub>	Turn on energy	V <sub>CC</sub> =600V, I <sub>c</sub> =75A, R <sub>G</sub> =15Ω, T <sub>j</sub> =125°C		20.6		mJ
E <sub>off</sub>	Turn off energy	V <sub>GE</sub> =±15V, L=60nH, inductive load		15.6		mJ
t <sub>d(on)</sub>	Turn-on delay time	V <sub>CC</sub> =600V, I <sub>c</sub> =75A		160		ns
t <sub>r</sub>	Rise time	V <sub>GE1</sub> =V <sub>GE2</sub> =±15V,		65		
t <sub>d(off)</sub>	Turn-off delay time	R <sub>G</sub> =15Ω		500		
t <sub>f</sub>	Fall time	inductive load		70		
V <sub>EC</sub>	Diode forward voltage	I <sub>c</sub> =-50A, V <sub>GE</sub> =0V			2.2	V
t <sub>rr</sub>	Reverse recovery time	I <sub>c</sub> =-50A, di/dt=-150A/μs			250	ns

## THERMAL RESISTANCE (T<sub>j</sub>=25°C, unless otherwise specified)

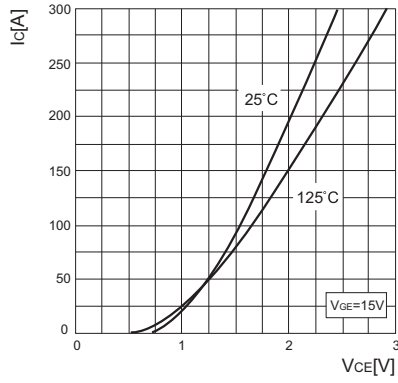
Symbol	Item	Condition	Min.	Typ.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance,	Per IGBT	—	—	0.18	°C / W
R <sub>th(j-c)</sub>	Junction to case	Per DIODE	—	—	0.35	
R <sub>th(c-h)</sub>	Contact thermal resistance	—	—	—	0.05	°C / W

## MECHANICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

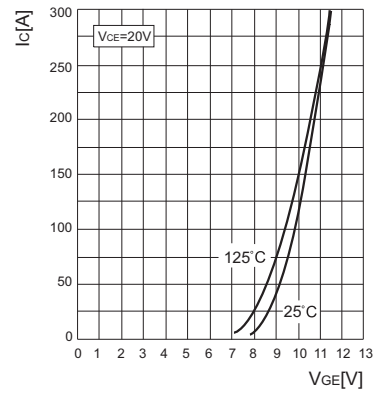
Symbol	Item	Condition	Min.	Typ.	Max.	Units
—	Screw torque	—	2	2.8	3.5	N·m
—	Weight	—	—	370	—	g

# CHARACTERISTIC CURVES

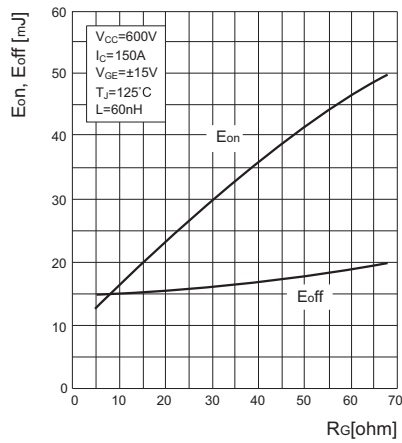
Collector-emitter voltage( $V_{CE}$ ) VS collector current( $I_c$ )



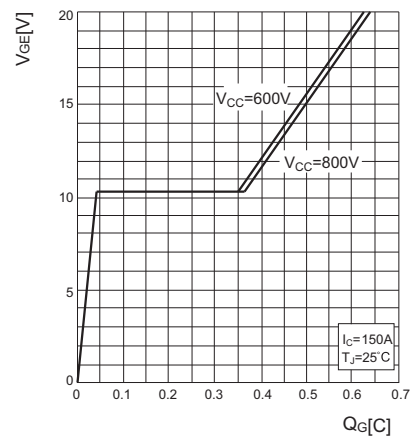
Typ. transfer characteristic



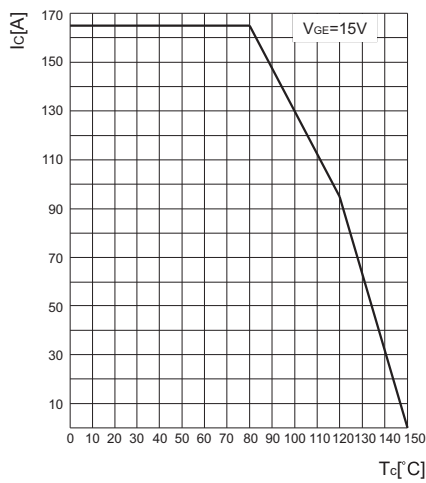
Typ. turn off energy and switching times versus gate resistor



Gate charge curve



Case temperature( $T_c$ )VS collector current( $I_c$ )



# HFS29/PM200D120(SA)

## MAXIMUM RATINGS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Rating	Unit
V <sub>CES</sub>	Collector-emitter voltage	G、E short	1200	V
V <sub>GES</sub>	Gate-emitter voltage	C、E short	±20	V
I <sub>C</sub>	Collector current	T <sub>C</sub> =80°C	205	A
I <sub>CP</sub>	Peak collector current		400	A
T <sub>PSC</sub>	Short circuit protection time	V <sub>CC</sub> =900V; V <sub>CEM</sub> <1200V V <sub>GE</sub> ≤15V; T <sub>j</sub> ≤125°C	10	s
V <sub>iso</sub>	Isolation voltage		2500	VAC
T <sub>j</sub>	Junction temperature		-40 ~ 150	°C
T <sub>stg</sub>	Storage temperature		-40 ~ 125	°C
I <sub>F</sub>	Diode forward current		200(130)	A
I <sub>FM</sub>	Diode peak forward current		400	A

## ELECTRICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Min.	Typ.	Max.	Units
I <sub>CES</sub>	Collector-emitter voltage	V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V		0.1	1.0	mA
I <sub>GES</sub>	Gate-emitter leakage current	V <sub>GE</sub> =±20V, V <sub>CE</sub> =0V, T <sub>j</sub> =125°C	-200		200	μA
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	I <sub>C</sub> =3mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>j</sub> =25°C	5	6.2	7	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>C</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =25°C		1.9		V
		I <sub>C</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =125°C		2.1		V
C <sub>ies</sub>	Input capacitance	V <sub>GE</sub> =0V, V <sub>CE</sub> =25V, f=1MHz		20		nF
C <sub>oes</sub>				1.6		
C <sub>res</sub>				1.0		
Q <sub>G</sub>	Total gate charge			2100		nC
R <sub>Gint</sub>	Resistance			4.5		Ω
E <sub>on</sub>	Turn on energy	V <sub>CC</sub> =600V, I <sub>C</sub> =75A, R <sub>G</sub> =15Ω, T <sub>j</sub> =125°C		24.8		mJ
E <sub>off</sub>	Turn off energy	V <sub>GE</sub> =±15V, L=60nH, inductive load		21.6		mJ
t <sub>d(on)</sub>	Turn-on delay time	V <sub>CC</sub> =600V, I <sub>C</sub> =75A		135		ns
t <sub>r</sub>	Rise time	V <sub>GE1</sub> =V <sub>GE2</sub> =±15V,		60		
t <sub>d(off)</sub>	Turn-off delay time	R <sub>G</sub> =15Ω		490		
t <sub>f</sub>	Fall time	inductive load		75		
V <sub>EC</sub>	Diode forward voltage	I <sub>C</sub> =-50A, V <sub>GE</sub> =0V			2.2	V
t <sub>rr</sub>	Reverse recovery time	I <sub>C</sub> =-50A, di/dt=-150A/μs			250	ns

## THERMAL RESISTANCE (T<sub>j</sub>=25°C, unless otherwise specified)

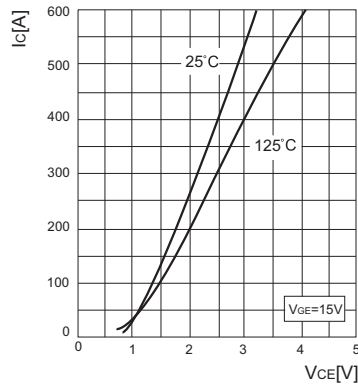
Symbol	Item	Condition	Min.	Typ.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance,	per IGBT	—	—	0.11	°C / W
R <sub>th(j-c)</sub>		per DIODE	—	—	0.32	
R <sub>th(c-h)</sub>	Contact thermal resistance	—	—	—	0.05	°C / W

## MECHANICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

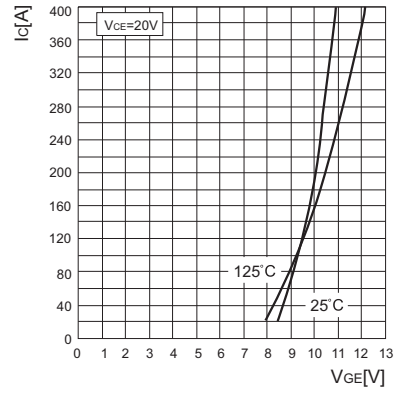
Symbol	Item	Condition	Min.	Typ.	Max.	Units
—	Screw torque	—	2	2.8	3.5	N·m
—	Weight	—	—	370	—	g

# CHARACTERISTIC CURVES

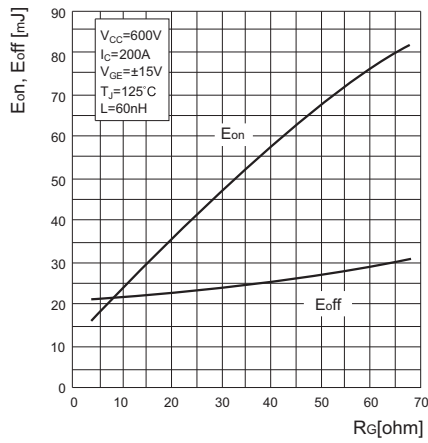
Collector-emitter voltage ( $V_{CE}$ ) VS collector current ( $I_c$ )



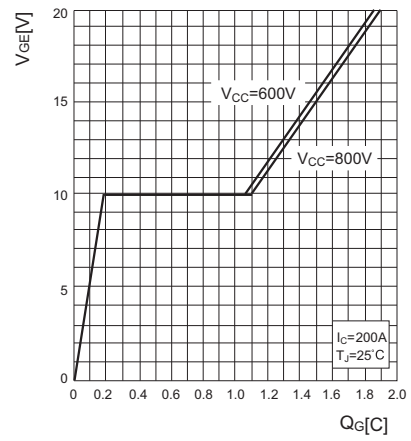
Typ. transfer characteristic



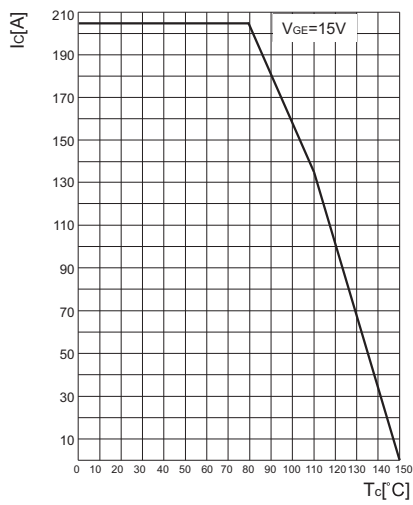
Typ. turn off energy and switching times versus gate resistor



Gate charge curve



Case temperature ( $T_c$ ) VS collector current ( $I_c$ )



# HFS29/PM300D120(SA)

## MAXIMUM RATINGS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Rating	Unit
V <sub>CEs</sub>	Collector-emitter voltage	G , E short	1200	V
V <sub>GES</sub>	Gate-emitter voltage	C , E short	±20	V
I <sub>c</sub>	Collector current	T <sub>c</sub> =80°C	260	A
I <sub>CP</sub>	Peak collector current		600	A
T <sub>PSC</sub>	Short circuit protection time	V <sub>CC</sub> =900V; V <sub>CEM</sub> <1200V V <sub>GE</sub> ≤15V; T <sub>j</sub> ≤125°C	10	s
V <sub>iso</sub>	Isolation voltage		2500	VAC
T <sub>j</sub>	Junction temperature		-40 ~ 150	°C
T <sub>stg</sub>	Storage temperature		-40 ~ 125	°C
I <sub>F</sub>	Diode forward current		300(190)	A
I <sub>FM</sub>	Diode peak forward current		600	A

## ELECTRICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

Symbol	Item	Condition	Min.	Typ.	Max.	Units
I <sub>CEs</sub>	Collector-cutoff current	V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V		0.1	1.0	mA
I <sub>GES</sub>	Gate-emitter leakage current	V <sub>GE</sub> =±20V, V <sub>CE</sub> =0V, T <sub>j</sub> =125°C	-200		200	μA
V <sub>GE(th)</sub>	Gate threshold voltage	I <sub>c</sub> =3mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>j</sub> =25°C	5	6.2	7	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>c</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =25°C		2.0		V
		I <sub>c</sub> =75A, V <sub>GE</sub> =15V, T <sub>j</sub> =125°C		2.3		V
C <sub>ies</sub>	Input capacitance	V <sub>GE</sub> = 0V, V <sub>CE</sub> =25V, f=1MHz		30		nF
C <sub>oes</sub>				2		
C <sub>res</sub>				1.6		
Q <sub>G</sub>	Total gate charge			3060		nc
R <sub>Gint</sub>	Resistance			3.5		Ω
E <sub>on</sub>	Turn on energy	V <sub>CC</sub> =600V, I <sub>c</sub> =75A, R <sub>G</sub> =15Ω, T <sub>j</sub> =125°C		33.4		mJ
E <sub>off</sub>	Turn off energy	V <sub>GE</sub> =±15V, L=60nH, inductive load		30.6		mJ
t <sub>d(on)</sub>	Turn-on delay time	V <sub>CC</sub> =600V, I <sub>c</sub> =75A		220		ns
t <sub>r</sub>	Rise time	V <sub>GE1</sub> =V <sub>GE2</sub> =±15V,		60		
t <sub>d(off)</sub>	Turn-off delay time	R <sub>G</sub> =15Ω		530		
t <sub>f</sub>	Fall time	inductive load		75		
V <sub>EC</sub>	Diode forward voltage	I <sub>c</sub> = -50A, V <sub>GE</sub> =0V			2.2	V
t <sub>rr</sub>	Reverse recovery time	I <sub>c</sub> = -50A, di/dt= -150A/μs			250	ns

## THERMAL RESISTANCE (T<sub>j</sub>=25°C, unless otherwise specified)

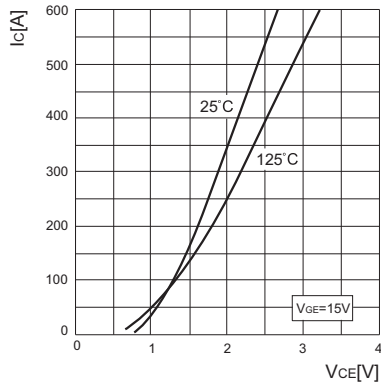
Symbol	Item	Condition	Min.	Typ.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance,	per IGBT	—	—	0.09	°C / W
R <sub>th(j-c)</sub>	Junction to case	per DIODE	—	—	0.24	
R <sub>th(c-h)</sub>	contact thermal resistance	—	—	—	0.05	°C / W

## MECHANICAL CHARACTERISTICS (T<sub>j</sub>=25°C, unless otherwise specified)

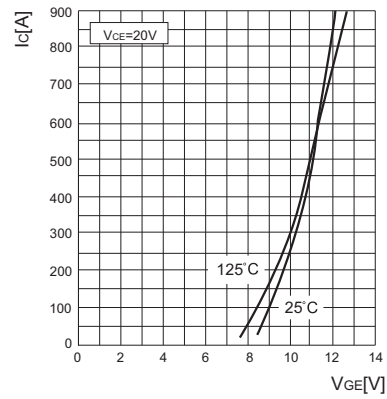
Symbol	Item	Condition	Min.	Typ.	Max.	Units
—	Screw torque	—	2.0	2.8	3.5	N·m
—	Weight	—	—	370	—	g

# CHARACTERISTIC CURVES

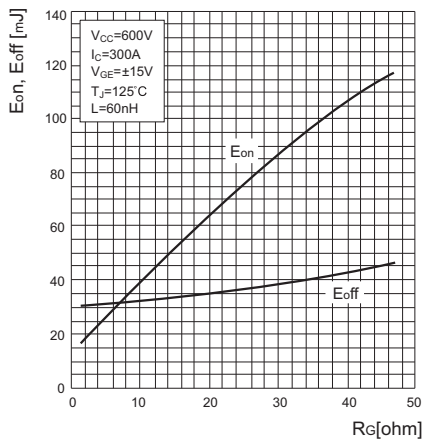
Collector-emitter voltage( $V_{CE}$ ) VS collector current( $I_c$ )



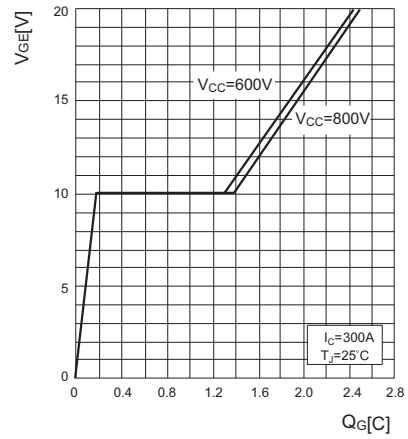
Typ. transfer characteristic



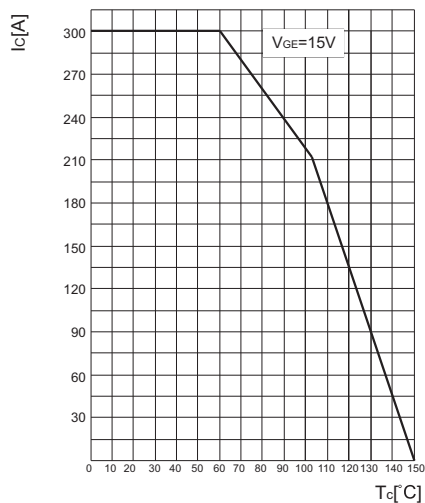
Typ. turn off energy and switching times versus gate resistor



Gate charge curve



Case temperature( $T_c$ )VS collector current( $I_c$ )



## Disclaimer

This datasheet is for the customers' reference. All the specifications are subject to change without notice.

We could not evaluate all the performance and all the parameters for every possible application. Thus the user should be in a right position to choose the suitable product for their own application. If there is any query, please contact Hongfa for the technical service. However, it is the user's responsibility to determine which product should be used only.